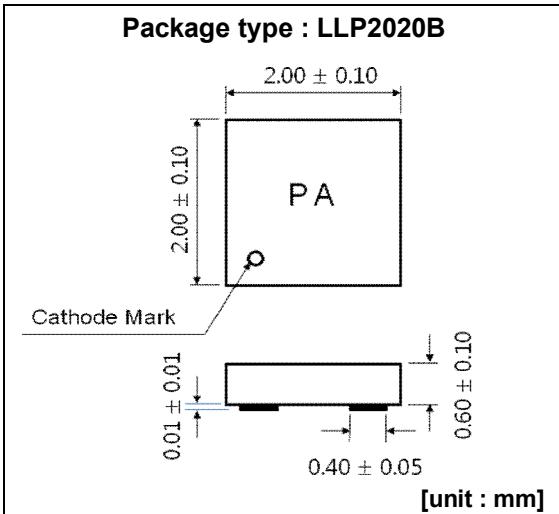


Features

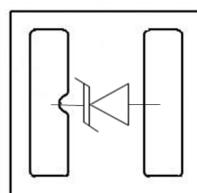
- Peak pulse power, $P_{PP} = 300W$ ($t_p = 10/1000 \mu s$)
- Suitable for surface-mounted design
- Reverse standoff voltage : 26V
- Low package height : 0.6 mm
- Halogen – free



Applications

- Power supply protection
- Automotive application
- Industrial application
- USB Vbus protection
- Power management

Schematic & PIN Configuration



Absolute Maximum Ratings at $T_A = 25^\circ C$

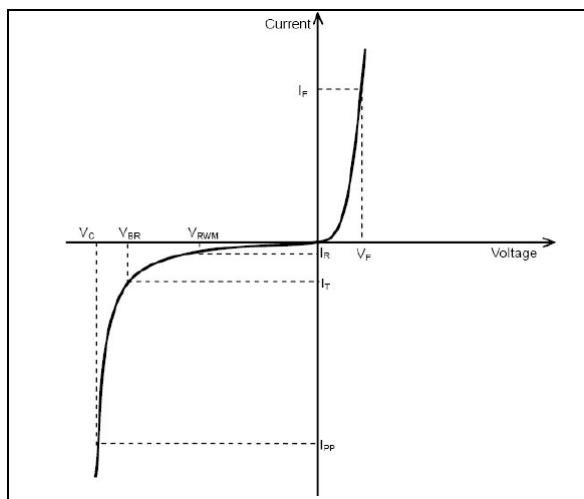
Rating	Symbol	Value	Unit
Peak Pulse Power ($t_p = 10/1000 \mu s$)	P_{PP}	300	Watts
Total Power Dissipation	P_D	500	mW
Maximum Peak Pulse Current ($t_p = 10/1000 \mu s$)	I_{PP}	9.5	Amps
ESD per IEC 61000-4-2 (air) ESD per IEC 61000-4-2 (contact)	V_{ESD}	± 30 ± 30	kV
Junction Temperature	T_J	-55 ~ 150	°C
Storage Temperature	T_{STG}	-55 ~ 150	°C

Electrical Characteristics at $T_A = 25^\circ C$

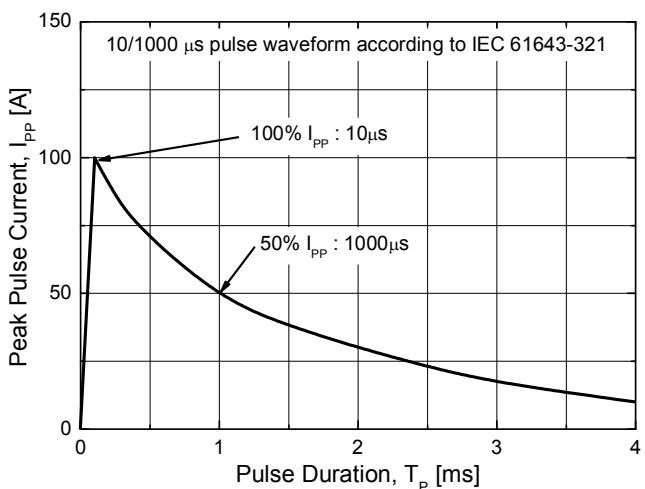
Parameter	Symbol	Conditions	Ratings			Unit
			Min	Typ	Max	
Reverse Stand-off Voltage	V_{RWM}				26	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1 \text{ mA}$	28		31.9	V
Reverse Leakage Current	I_R	$V_{RWM} = 26 \text{ V}, T = 25^\circ C$			0.1	µA
Forward Voltage	V_F	$I_F = 10 \text{ mA}$	0.6	0.8	1.2	V
Clamping Voltage	V_C	$I_{PP} = 9.5 \text{ A}, t_p = 10/1000 \mu s$			40	V

Electrical Characteristics

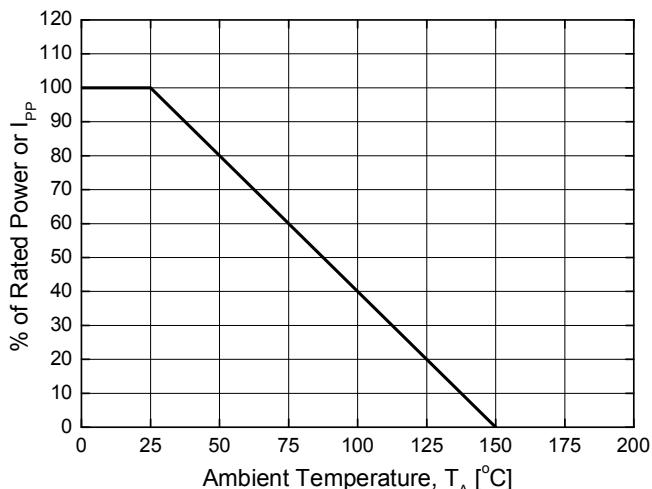
Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F
P_{PP}	Peak Power Dissipation



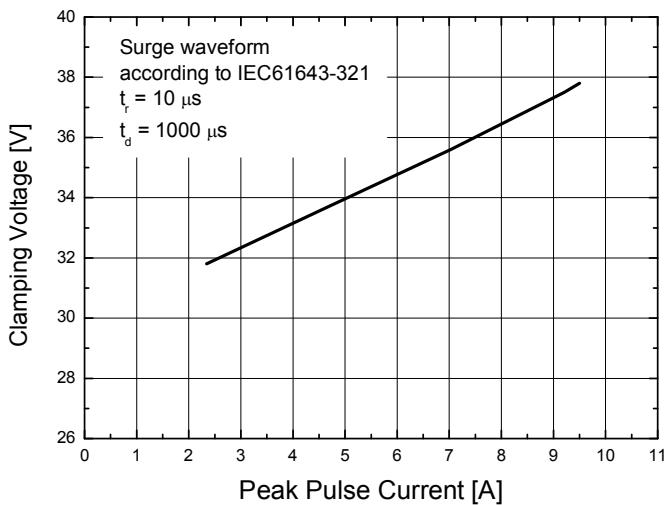
Peak Pulse Waveform



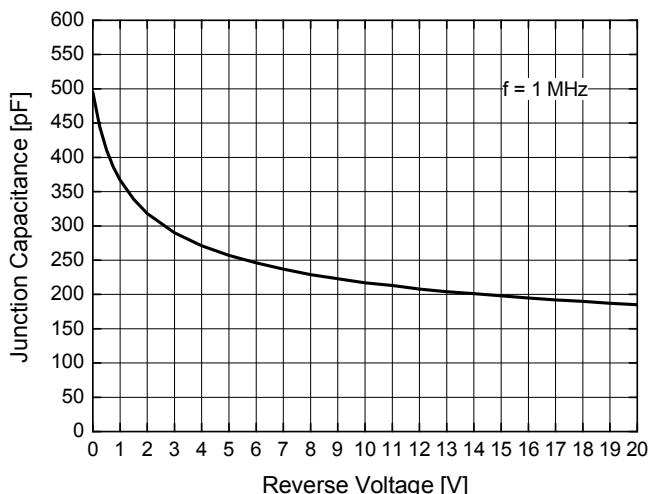
Power Derating Curve



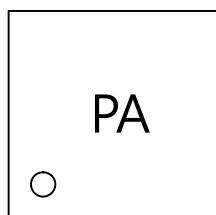
Clamping Voltage vs. Peak Pulse Current



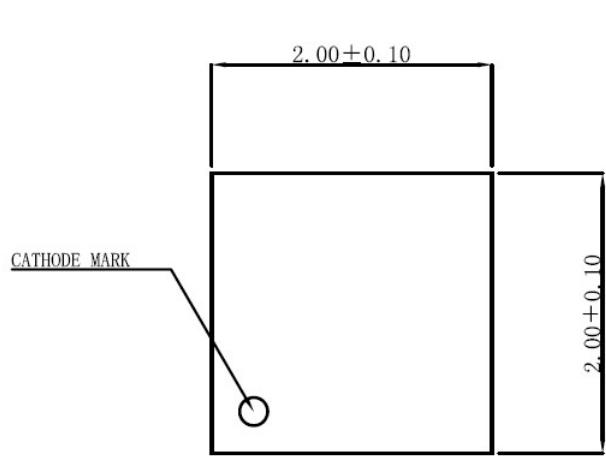
Junction Capacitance vs. Reverse Voltage



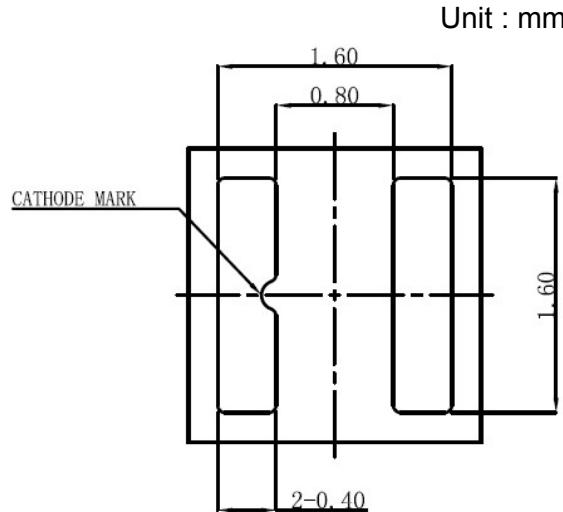
Marking Code



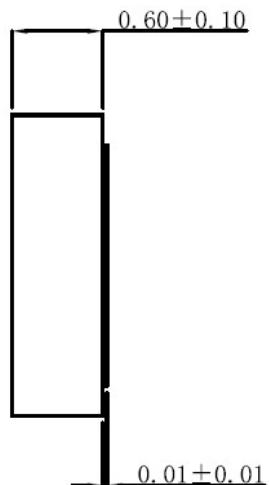
Package Dimensions



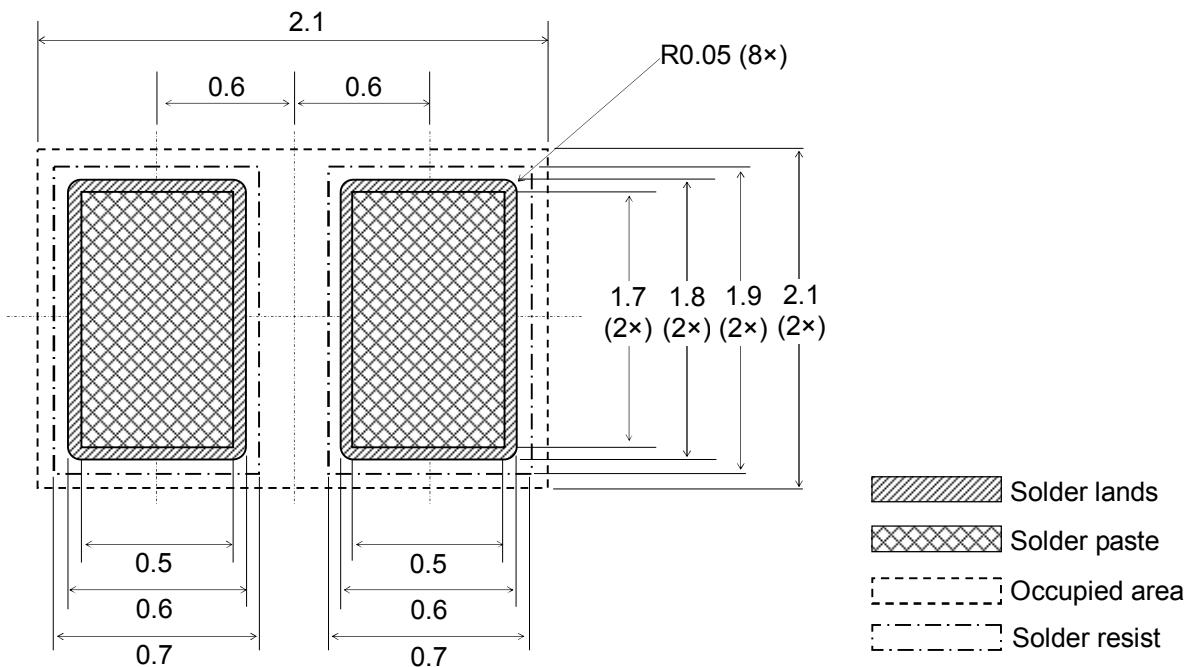
Top view



Bottom view



Side view

Soldering

Unit : mm